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## 1.0 OBJECTIVE

This specification defines the performance, test, quality and reliability requirements of 0.5mm pitch BergStak HS<sup>TM</sup> product.

#### 2.0 SCOPE

This specification is applicable to the termination characteristics of 0.5mm pitch BergStak HS<sup>TM</sup> family of products (receptacle with plug mating height 5mm to 12.0mm), with 30u" Palladium-Nickel plating and 8u" Min-Au plating, which provides electrical connections between parallel mounted boards.

## 3.0 GENERAL

This document is composed of the following sections:

<b>PARAGRAPH</b>	<u>TITLE</u>
1.0	OBJECTIVE
2.0	SCOPE
3.0	GENERAL
4.0	APPLICABLE DOCUMENTS
4.1	Standards and Specifications
5.0	REQUIREMENTS
5.1	Qualification
5.2	Material
5.3	Finish
5.4	Design and Construction
5.5	Rating
6.0	PERFORMANCE
6.1	Performance
6.2	Test Methods
6.3	Test Sequence

# 4.0 APPLICABLE DOCUMENTS

- 4.1 Standards and Specifications
  - 4.1.1MIL-STD-202: Test methods for electronic and electrical component parts.
  - 4.1.2MIL-STD-1344: Test methods for electronic connectors.
  - 4.1.3EIA 364: Electronic connector/socket test procedures including environmental classifications.
  - 4.1.4QQ-N-290: Nickel plating.
  - 4.1.5MIL-G-45204: Gold plating electrodeposited
  - 4.1.6MIL-C-45662: Calibration system requirements

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#### 5.0 REQUIREMENTS

### 5.1 Qualification

Connectors furnished under this specification shall be capable of meeting the qualification test equirements specified herein.

#### 5.2 Material

- 5.2.1 Housing: All housing materials shall be high temperature plastic, rated flame retardant 94V-0 in accordance with UL-94.
- 5.2.2 Receptacle Terminal: Corson Alloy
- 5.2.3Plug Terminal: Corson Alloy.
- 5.2.4Sticking tape: Polyimide.
- 5.2.5Hold Down: Brass.

#### 5.3 Finish

The finish for applicable components shall be specified in product drawings with plating area, plating material and plating thickness.

## 5.4 The thickness of the PCB solder paste

Below data is FCI recommended dimension, For some customer's process are different (such as, PCB thickness, solder temperature, solder paste type, etc.), customer can according to the actual application environment adjust the solder paste thickness.

- 5.4.1 The position less than 120pin,recommend using solder paste thickness 0.15mm Min.
- 5.4.2 The position greater than or equal to 120pin,recommend using solder paste thickness 0.18mm Min.

#### 5.5 Design and Construction

The connector shall be a multi-piece assembly having two rows of contacts with surface mount soldertail terminations for installation on printed wiring board.

### 5.6 Rating

Voltage Rating	50V AC
Current Rating	0.5A Max.
Temperature Rating	-40°C ~ 125°C

#### 6.0 PERFORMANCE

Unless otherwise specified, the performance of connectors given in the attached list shall satisfy the values specified in Table 6.1. The performance test shall follow the test method and the test sequence given in Table 6.2 & 6.3 under the environmental conditions listed below. All connectors to be tested shall be free of defects such as burr, flaw, void, blister etc. which will affect the life and application of connectors.

- Temperature ----- 15°C ~ 35°C
- Humidity ----- 25% ~ 85%
- Pressure ------ 86 ~ 106KPa

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### 6.1 Performance

#### TABLE 6.1

	I ABLE 6.1					
	Test Item	Requirements				
6.1.1	Visual Examination	Product shall meet the requirements of product drawings. Visual Examination performed under 10X magnification. Parts should be free from blistering, discoloration, cracks, etc				
	Electric Requirements					
6.1.2	Low Level Contact Resistance(LLCR)	Initial 50 mς Maximum After test 70 mς Maximum				
6.1.3	Dielectric Withstanding Voltage	No evidence of arc-cover, insulation breakdown or leakage current in excess of 1 mA.				
6.1.4	Insulation Resistance	100 Mς Minimum				
6.1.5	Current Rating	Temperature rise above ambient shall not exceed 30°C with all contacts powered at 0.5A				
	Mechanical Requiremen	ts				
6.1.6	Vibration	Initial 50 mς Maximum After test 70 mς Maximum No discontinuity greater than 1 microsecond				
6.1.7	Shock	Initial 50 mς Maximum After test 70 mς Maximum No discontinuity greater than 1 microsecond				
6.1.8	Mating Force	0.9N (90 gramf) Maximum per contact.				
6.1.9	Un-mating Force	0.1N (10 gramf) Minimum per contact.				
6.1.10	Durability	Initial 50 mς Maximum After test 70 mς Maximum				
6.1.11	Solderability	Solder coverage 95% Minimum				
6.1.12	Resistance to Solder Heat	No evidence of physical or mechanical damage.				
6.1.13	Contact Retention Force	1N Minimum per contact.				
6.1.14	Reseating	Manually unplug/plug the mated connector assembly.				
	Environmental Requiren	nents				
6.1.15	Thermal Shock	Initial 50 mς Maximum After test 70 mς Maximum				
6.1.16	Temperature Life	Initial 50 mς Maximum After test 70 mς Maximum				
6.1.17	Cyclical Humidity & Temperature	Initial 50 mς Maximum After test 70 mς Maximum				
6.1.18	Mixed Flow Gas	Initial 50 mς Maximum After test 70 mς Maximum				
6.1.19	Thermal Disturbance	Initial 50 mg Maximum After test 70 mg Maximum				

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# 6.2 Test Methods

# TABLE 6.2

	Test Item	Test Methods
6.2.1	Visual Examination	Visually and functionally inspected. Under 10X magnification.
6.2.2	Low Level Contact Resistance(LLCR)	Fig 1. Test method of contact resistance mesuring  EIA-364-23  Test method of connection as Figure 1.  Test current
6.2.3	Dielectric Withstanding Voltage	EIA-364-20 Method B, Test Condition I  Test voltage 300 Vrms AC  Duration 1 minute  Measure between adjacent terminals of mated connectors.  Number of readings 30 (10 readings per connector set)
6.2.4	Insulation Resistance	EIA-364-21 Test voltage 150 V DC Duration 1 minute Measure between adjacent terminals of mated connectors. Number of readings 30 (10 readings per connector set)
6.2.5	Current Rating	EIA-364-70 Ambient still air 25°C All contact powered 0.5A

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EIA-364-28 Test Condition V, Letter D   Frequency			
Overall rms g			Frequency 50 to 2000 Hz
Duration	6.2.6	Vibration	
EIA-364-27, Test Condition A   Accelerated velocity 490 m/s² (50G).   Waveform half-sine shock pulse.   Duration 11.3 feet per second   Number of cycles	0.2.0	1.5.5	
Accelerated velocity 490 m/s² (50G). Waveform			· · · · · · · · · · · · · · · · · · ·
Accelerated velocity 490 m/s² (50G). Waveform			
Waveform			
Calcal   C			Accelerated velocity 490 m/s* (50G).
Velocity change	627	Shock	
Number of cycles	0.2.7	Griock	
6.2.8 Mating Force    EIA-364-13			
Operating speed 25 mm/minute No lubrication and utilize free-floating fixture. Number of connectors 5 mated pair			,
Solderability   Solderability   Solderability   Solder temperature			
Number of connectors 5 mated pair	0.00	Matina Fana	
EIA-364-13   Operating speed 25 mm/minute   No lubrication and utilize free-floating fixture.   Number of connectors 5 mated pair	6.2.8	Mating Force	
Operating speed 25 mm/minute No lubrication and utilize free-floating fixture. Number of connectors 5 mated pair  EIA-364-09 Operating speed 25 mm/minute Number of cycles 100 Pre-Conditioning cycles 25 For leaded: Solder temperature 3± 0.5 seconds Flux immersion 5 to 10 seconds Flux and solder material are defined in MIL-STD-202, method 208  For Non- leaded: Solder temperature 5 to 10 seconds Flux immersion			Number of confectors 5 mated pair
6.2.9 Un-mating Force  No lubrication and utilize free-floating fixture. Number of connectors 5 mated pair  EIA-364-09 Operating speed 25 mm/minute Number of cycles 100 Pre-Conditioning cycles 25 For leaded: Solder temperature 3± 0.5 seconds Flux immersion duration 5 to 10 seconds Flux and solder material are defined in MIL-STD-202, method 208  For Non- leaded: Solder temperature 260 ± 5°C. Immersion duration 3± 0.5 seconds Flux and solder material are defined in MIL-STD-202, method 208  For Non- leaded: Solder temperature 5 to 10 seconds Flux immersion duration 3± 0.5 seconds Flux immersion duration 3± 0.5 seconds Flux and solder material are defined in MIL-STD-202, method 208  For leaded: Peak temperature 240 ± 5°C.			EIA-364-13
Number of connectors 5 mated pair    EIA-364-09			
6.2.10 Durability    EIA-364-09	6.2.9	Un-mating Force	
Operating speed 25 mm/minute Number of cycles 100 Pre-Conditioning cycles 25  For leaded: Solder temperature 230 ± 5°C. Immersion duration 5 to 10 seconds Flux immersion 5 to 10 seconds Flux and solder material are defined in MIL-STD-202, method 208  6.2.11 Solderability  For Non- leaded: Solder temperature 260 ± 5°C. Immersion duration 3 ± 0.5 seconds Flux immersion duration 5 to 10 seconds Flux immersion duration 5 to 10 seconds Flux and solder material are defined in MIL-STD-202, method 208  For leaded: Peak temperature 240 ± 5°C.			Number of connectors 5 mated pair
Operating speed 25 mm/minute Number of cycles 100 Pre-Conditioning cycles 25  For leaded: Solder temperature 230 ± 5°C. Immersion duration 5 to 10 seconds Flux immersion 5 to 10 seconds Flux and solder material are defined in MIL-STD-202, method 208  6.2.11 Solderability  For Non- leaded: Solder temperature 260 ± 5°C. Immersion duration 3 ± 0.5 seconds Flux immersion duration 5 to 10 seconds Flux immersion 5 to 10 seconds Flux and solder material are defined in MIL-STD-202, method 208  For leaded: Peak temperature 240 ± 5°C.			EIA-364-09
Number of cycles 100 Pre-Conditioning cycles 25  For leaded: Solder temperature 3± 0.5 seconds Flux immersion 5 to 10 seconds Flux and solder material are defined in MIL-STD-202, method 208  For Non- leaded: Solder temperature 260 ± 5°C. Immersion duration 5 to 10 seconds Flux immersion 5 to 10 seconds Flux immersion 5 to 10 seconds Flux and solder material are defined in MIL-STD-202, method 208  For leaded: Peak temperature 240 ± 5°C.	0.040	Dunch Hite	
For leaded: Solder temperature 230 ± 5°C. Immersion duration 3± 0.5 seconds Flux immersion 5 to 10 seconds Flux and solder material are defined in MIL-STD-202, method 208  6.2.11 Solderability  For Non- leaded: Solder temperature 260 ± 5°C. Immersion duration 3± 0.5 seconds Flux immersion 5 to 10 seconds Flux immersion 5 to 10 seconds Flux and solder material are defined in MIL-STD-202, method 208  For leaded: Peak temperature 240 ± 5°C.	6.2.10	Durability	
Solder temperature 230 ± 5°C.  Immersion duration 3± 0.5 seconds Flux immersion 5 to 10 seconds Flux and solder material are defined in MIL-STD-202, method 208  For Non- leaded: Solder temperature 260 ± 5°C.  Immersion duration 5 to 10 seconds Flux immersion 5 to 10 seconds Flux and solder material are defined in MIL-STD-202, method 208  For leaded: Peak temperature 240 ± 5°C.			
Immersion duration 3± 0.5 seconds Flux immersion 5 to 10 seconds Flux and solder material are defined in MIL-STD-202, method 208  For Non- leaded: Solder temperature 260 ± 5°C. Immersion duration 5 to 10 seconds Flux immersion 5 to 10 seconds Flux and solder material are defined in MIL-STD-202, method 208  For leaded: Peak temperature 240 ± 5°C.			
Flux immersion 5 to 10 seconds Flux and solder material are defined in MIL-STD-202, method 208  For Non- leaded: Solder temperature 260 ± 5°C. Immersion duration 5 to 10 seconds Flux immersion 5 to 10 seconds Flux and solder material are defined in MIL-STD-202, method 208  For leaded: Peak temperature 240 ± 5°C.			· ·
Flux and solder material are defined in MIL-STD-202, method 208 For Non- leaded: Solder temperature $260 \pm 5^{\circ}$ C. Immersion duration $3 \pm 0.5$ seconds Flux immersion $5$ to 10 seconds Flux and solder material are defined in MIL-STD-202, method 208 For leaded: Peak temperature $240 \pm 5^{\circ}$ C.			
6.2.11 Solderability For Non- leaded: Solder temperature $260 \pm 5^{\circ}$ C. Immersion duration $3 \pm 0.5$ seconds Flux immersion $5$ to 10 seconds Flux and solder material are defined in MIL-STD-202, method 208 For leaded: Peak temperature $240 \pm 5^{\circ}$ C.			
Solder temperature 260 ± 5°C.  Immersion duration 3± 0.5 seconds  Flux immersion 5 to 10 seconds  Flux and solder material are defined in MIL-STD-202, method 208  For leaded:  Peak temperature 240 ± 5°C.		0.111.	Tidx and solder material are defined in Mile-01D-202, method 200
Immersion duration 3± 0.5 seconds Flux immersion 5 to 10 seconds Flux and solder material are defined in MIL-STD-202, method 208  For leaded: Peak temperature 240 ± 5°C.	6.2.11	Solderability	For Non- leaded:
Flux immersion 5 to 10 seconds Flux and solder material are defined in MIL-STD-202, method 208  For leaded: Peak temperature 240 ± 5°C.			Solder temperature 260 ± 5°C.
Flux and solder material are defined in MIL-STD-202, method 208  For leaded: Peak temperature 240 ± 5°C.			Immersion duration 3± 0.5 seconds
For leaded: Peak temperature 240 ± 5°C.			
Peak temperature 240 ± 5°C.			Flux and solder material are defined in MIL-STD-202, method 208
Peak temperature 240 ± 5°C.			For leaded:
6.2.12 Resistance to Solder Heat	6212	Resistance to Solder Heat	
	0.2.12	Toolotarioe to colder Fleat	
Peak temperature 260 ± 5°C.			
Duration 30 seconds			Duration 30 seconds
Operating speed 25 mm/minute	0.0.10	Octor Date ii 5	Operating speed 25 mm/minute
	6.2.13	Contact Retention Force	Number of readings 30 (10 readings per connector set)

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6.2.14	Reseating	Perform 3 cycles mate/unmate
6.2.15	Thermal Shock	EIA-364-32 Method A Temperature range40 +0/-5°C to 125 +5/-0°C Time at temperature extremes 30 minutes Test Duration (A-4) 10 cycles Transfer Time 5 minutes maximum
6.2.16	Temperature Life	EIA-364-17 Method A, Test Condition 4  Temperature 105 ±5°C.  Duration Condition D 1,000 hours.  Plug & receptacle to remain mated without electrical load.  LLCR measured @ Initial, 250, 500, 750 and 1,000 hours  Pre-Conditioning Temperature 105 ±5°C  Pre-Conditioning Duration 120 hours
6.2.17	Cyclical Humidity & Temperature	65'c  -10'c  -10
6.2.18	Mixed Flow Gas	Duration 10 cycles.  EIA-364-65, Class IIA  Temperature: 30°C  Relative Humidity: 70%  Concentration: H <sub>2</sub> S 10 ppb  NO <sub>2</sub> 200 ppb  CL <sub>2</sub> 10 ppb  SO <sub>2</sub> 100 ppb  Test duration: 1) 7days unmated (Both halves are exposed to gas) and 7days mated 2) 14days mated  **Test Group 10 is only applicable to parts with 30u GXT.
6.2.19	Thermal Disturbance	EIA-364-1000 Table 4, Test Group 4  Cycle the mated connectors between 15 ± 3°C and 85 ± 3°C as measured on the part. Ramps should be a minimum of 2°C per

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minute, and dwell times should insure that the contacts reach the temperature extremes (a minimum of 5 minutes). Humidity is not controlled.
Perform 10 cycles.

# 7.0 QUALIFICATION TEST MATRIX

Table 7.1

TEST ITEM	TEST GROUP										
1201112111	Section	1	2	3	4	5	6	7	8	9	10
Visual Examination	6.1.1	1	1	1 11	1	1	1 3	1	1	1	1
Low Level Contact Resistance (LLCR)	6.1.2	2 5 7 9	2 4 6 8 10	3 10				2 4 6 8 10	2 4 6 8	2 4 6 8 10 12	2 4 6 8 10 12 14
Dielectric Withstanding Voltage	6.1.3	3 11									
Insulation Resistance	6.1.4	4 10									
Current Rating	6.1.5	12									
Vibration	6.1.6		7								
Shock	6.1.7		9								
Mating Force	6.1.8			2 5 8							
Un-mating Force	6.1.9			4 6 9							
Durability Pre-conditioning	6.1.10	6	3					3	3	3	3
Durability	6.1.10			7							
Solderability	6.1.11					2					
Resistance To Solder Heat	6.1.12						2				
Contact Retention Force	6.1.13				2						
Reseating	6.1.14							9	7	11	13
Thermal Shock	6.1.15							5			
Temperature Life Pre- Conditioning	6.1.16		5							5	5
Temperature Life	6.1.16								5		
Cyclical Humidity & Temperature	6.1.17	8						7			
Mixed Flowing Gas 7 days unmated	6.1.18										7

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Mixed Flowing Gas 7 days mated	6.1.18										9
Mixed Flowing Gas 14 days mated	6.1.18									7	
Thermal Disturbance	6.1.19									9	11
Number of Samples		3/3	3	5	3	3	3	3	3	3	5

#### **NOTICE** 8.0

Please be sure to look through application specification (GS-20-0507) of relevance in the case of use of this product.

The document may be changed without prior notice.

#### **RECORD RETENTION** 9.0

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